SATURN ELECTRONICS DFM REQUIREMENTS

COPPER LAYERS

DFM	1.5 OUNCE FINISHED COPPER MINIMUM	1.5 OUNCE FINISHED COPPER PREFERRED	2 OUNCE FINISHED COPPER MINIMUM	2 OUNCE FINISHED COPPER PREFERRED	3 OUNCE FINISHED COPPER MINIMUM	3 OUNCE FINISHED COPPER PREFERRED
PAD TO PAD	5	6	6	7	8	9
PAD TO CIRCUIT	5	6	6	7	8	9
CIRCUIT TO CIRCUIT	5	6	6	7	8	9
LINE WIDTH	4	5	5	6	7	8
THERMAL SPOKE WIDTH	7	10	8	10	10	12
THERMAL MOAT WIDTH	10	12	10	12	10	12

	ANY COPPER WEIGHT		
NPTH TO PAD	10	10	
NPTH TO CIRCUIT	10	10	
ROUT TO COPPER	5	7	
SCORED EDGE TO COPPER	15	15	
PTH TO COPPER (INNER LAYERS)	10	12	
PTH ANNULAR RING	5	7	APPLIES TO DRILL SIZE. FORMULA IS: (FINISHED HOLE SIZE + 15 MILS)
VIA ANNULAR RING	5	7	VIAS ARE TREATED AS +.000/-HOLE SIZE

SOLDERMASK

DFM		
NPTH ANNULAR RING	10	14
VIA PAD ANNULAR RING	0	0
PTH PAD ANNULAR RING	2	3
SMD ANNULAR RING	2	3
MASK DAM	3	3
COVERAGE	2	3

SILKSCREEN

MINIMUM LINE WIDTH	5	5